

## Switch-mode Power Rectifier

# D<sup>2</sup>PAK Surface Mount Power Package

### MBRB1545CTG, SBRB1545CTG

The D<sup>2</sup>PAK Power Rectifier employs the Schottky Barrier principle with a platinum barrier metal. These state-of-the-art devices have the following features:

#### **Features**

- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94, V-0 @ 0.125 in
- Short Heatsink Tab Manufactured Not Sheared
- Similar in Size to the Industry Standard TO220 Package
- SBRB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant\*

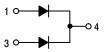
#### **Mechanical Characteristics**

- Case: Epoxy, Molded, Epoxy Meets UL 94, V-0
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings:
  - ◆ Machine Model = C (> 400 V)
  - ♦ Human Body Model = 3B (> 8000 V)

# SCHOTTKY BARRIER RECTIFIER 15 AMPERES 45 VOLTS



D<sup>2</sup>PAK CASE 418B STYLE 3



#### MARKING DIAGRAM



B1545 = Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package
AKA = Diode Polarity

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 3.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### MBRB1545CTG, SBRB1545CTG

#### MAXIMUM RATINGS (Per Leg)

Symbol	Rating	Value	Unit
V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	45	V
I <sub>F(AV)</sub>	$I_{F(AV)} \qquad \text{Average Rectified Forward Current} \\ \text{(Rated V}_{R}, T_{C} = 167^{\circ}\text{C}) \text{ Total Device}$ $I_{FRM} \qquad \text{Peak Repetitive Forward Current} \\ \text{(Rated V}_{R}, \text{Square Wave, 20 kHz, T}_{C} = 166^{\circ}\text{C})$		Α
I <sub>FRM</sub>			Α
I <sub>FSM</sub>	Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	150	Α
I <sub>RRM</sub>	Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	1.0	Α
T <sub>stg</sub>	Storage Temperature Range	-65 to +175	°C
T <sub>J</sub>	Operating Junction Temperature (Note 1)	-65 to +175	°C
dv/dt	Voltage Rate of Change (Rated V <sub>R</sub> )	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS (Per Leg)

Symbol	Symbol Characteristic		Unit
$R_{ heta JC} \ R_{ heta JA}$	Thermal Resistance Junction to Case Junction to Ambient (Note 2)	2.0 50	°C/W

<sup>2.</sup> When mounted using minimum recommended pad size on FR-4 board.

#### **ELECTRICAL CHARACTERISTICS** (Per Leg)

Symbol	Characteristic	Value	Unit
V <sub>F</sub>	Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 7.5 \text{ Amps}$ , $T_J = 125^{\circ}\text{C}$ ) ( $i_F = 15 \text{ Amps}$ , $T_J = 125^{\circ}\text{C}$ ) ( $i_F = 15 \text{ Amps}$ , $T_J = 25^{\circ}\text{C}$ )	0.57 0.72 0.84	V
i <sub>R</sub>	Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J$ = 125°C) (Rated dc Voltage, $T_J$ = 25°C)	15 0.1	mA

<sup>3.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction–to–Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

#### MBRB1545CTG, SBRB1545CTG

#### **TYPICAL CHARACTERISTICS**

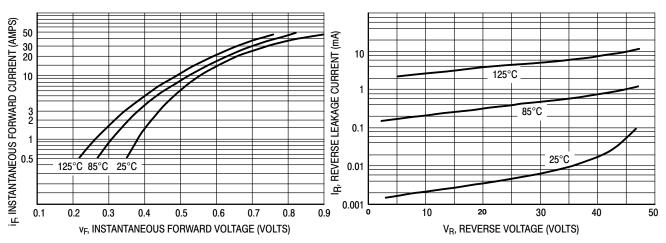


Figure 1. Typical Forward Voltage, Per Leg

Figure 2. Typical Reverse Current, Per Leg

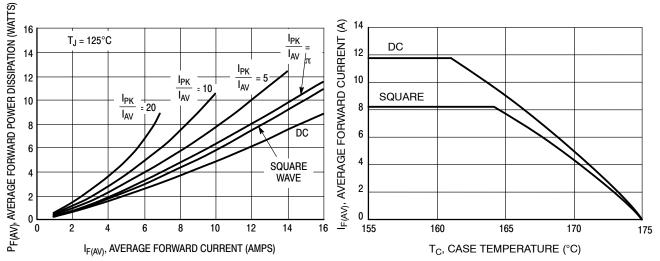


Figure 3. Typical Forward Power Dissipation

Figure 4. Current Derating, Case, Per Leg

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MBRB1545CTT4G	D <sup>2</sup> PAK (Pb-Free)	800 / Tape & Reel
SBRB1545CTT4G	D <sup>2</sup> PAK (Pb-Free)	800 / Tape & Reel

#### **DISCONTINUED** (Note 4)

MBRB1545CTG	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail	
SBRB1545CTG	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <a href="https://example.com/BRD8011/D">BRD8011/D</a>.

<sup>4.</sup> **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on <a href="https://www.onsemi.com">www.onsemi.com</a>.

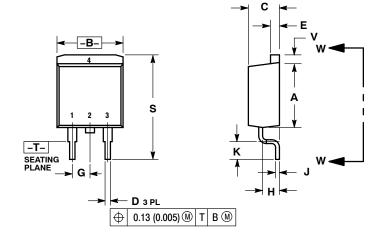




D<sup>2</sup>PAK 3 CASE 418B-04 ISSUE L

**DATE 17 FEB 2015** 

#### SCALE 1:1



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
- CONTROLLING DIMENSION: INCH.
   418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC 2.54		2.54	BSC
Н	0.080	0.110	2.03	2.79
7	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
М	0.280	0.320	7.11	8.13

0.039 REF 0.99 REF 0.575 0.625 14.60 15.88

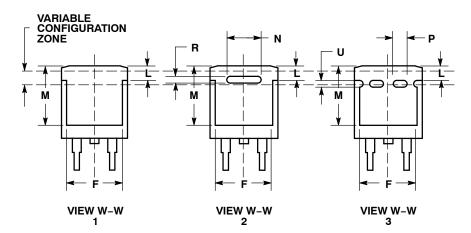
V 0.045 0.055 1.14 1.40

2.00 REF

0.197 REF

0.079 REF

R



STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

STYLE 4: PIN 1. GATE E 2. COLLECTOR

2. COLLECTOR 3. EMITTER 4. COLLECTOR STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE

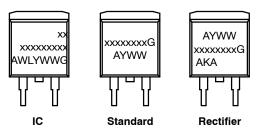
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# GENERIC MARKING DIAGRAM\*

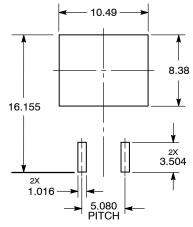


xx = Specific Device Code A = Assembly Location

WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package
AKA = Polarity Indicator

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

#### **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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